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(54) ELECTROLYTIC COPPER FOIL WITH CARRIER FOIL, ITS PRODUCING METHOD AND COPPER-COVERED LAMINATED SHEET USING THE ELECTROLYTIC COPPER FOIL WITH CARRIER FOIL

(57)Abstract:

PROBLEM TO BE SOLVED: To stabilize the peeling between carrier foil and a copper foil layer composed only of fine copper grains on the joined boundary as to electrolytic copper foil with carrier foil using an organic series material on the joined boundary between the carrier foil and the copper foil.

SOLUTION: (1) a barrier copper layer is formed on a joined boundary layer, and a fine copper grain layer is formed on the barrier copper layer. (2) Rust preventing treatment to the surface of the fine copper grain layer is executed by using a plating bath having a composition of a single metal or an alloy whose deposition potential is nobler than -900 mV (the value in the case of using an AgCl<sub>2</sub>/Ag reference electrode). (3) Electrolytic copper foil with carrier foil obtained by combining the means (1) and (2) is made. By adopting any means thereamong, problem is solved.